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Attorney Docket No. 108298634US1
Disclosure No. 01-0327.01

O P E R A T I O N S C E N T R E
AUG 13 2004 INFORMATION DISCLOSURE STATEMENT BY APPLICANT
Form PTO-1449 (Modified)
(Use several sheets if necessary)

COMPLETE IF KNOWN			
Sheet	1	of	1
			Attorney Docket No. 108298634US1
Application Number	10/674,869		
Confirmation Number	6310		
Filing Date	26 September 2003		
First Named Inventor	Leng Nam Yin		
Group Art Unit	2014-2822		
Examiner Name	Wael M. Fahmy K. DUCONG		

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
KFD		6,521,993		Masayuki et al.	02/18/2003	

EXAMINER 	DATE CONSIDERED 
*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).	

Express Mail No. EV335523071US

Attorney Docket No. 108298634US1

Disclosure No. 01-0327.01

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

Form PTO-1449 (Modified)
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Sheet

1

of

2

COMPLETE IF KNOWN

Application Number	10/673,869
Confirmation Number	6310
Filing Date	28 September 2003
First Named Inventor	Leng Nam Yin
Group Art Unit	2822
Examiner Name	K. Duong

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U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
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		Office	NUMBER	Kind Code (if known)				
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EXAMINER

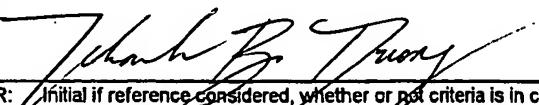
DATE CONSIDERED

9/28/2004

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT Form PTO-1449 (Modified) (Use several sheets if necessary)				COMPLETE IF KNOWN	
Sheet	2	of	2	Application Number	10674869
				Confirmation Number	
				Filing Date	26 September 2003
				First Named Inventor	Leng Nam Yin
				Group Art Unit	
				Examiner Name	
				Attorney Docket No.	108298634US1

OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.			
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		QIN, Ivy Wei et al., "Wedge Bonding for Ultra Fine Pitch Applications," 10 pages, originally presented at Semicon Singapore 2001, retrieved from the Internet on August 18, 2001, < http://www.kns.com/resources/articles/wedge-ultra-fine-pitch.pdf >.			
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